

Amendments to the Specification:

Please replace the paragraph bridging pages 5 and 6 with the following amended paragraph:

Yet another solution to this problem is to use a cleaning polish etch solution/process (a process performed by running disk substrates on a polishing pad using an etch solution instead of a slurry, i.e., there are no slurry particles in the cleaning polish etch solution) with acid, neutral or base solutions to etch the glass substrate and/or the attached slurry particles under polish conditions thereby maintaining the superfinish surface while removing the superfinish polish slurry debris by etching and dilution. Such a cleaning polish etch solution/process is as disclosed in the copending application ~~_____, 09/976,408~~ (docket no. ROC920010283US1) entitled "CLEANING POLISH ETCH COMPOSITION AND PROCESS FOR A SUPERFINISHED SURFACE OF A SUBSTRATE", assigned to the same assignee as the present application, and filed concurrently with the present application. Etching by itself (i.e., the first solution discussed above) with PVA scrub, ultrasonics or megasonics is what has been done to remove slurry particles from Al/Mg-NiP or glass substrates, but with the less than 20 nm glide heights now in use, a cleaning polish etch solution/process is needed to ensure 100% surface cleaning of particles that small (i.e., the lower the glide height, the smaller the particles needing to be removed, and thus the more difficult they are to remove) while maintaining the surface finish. The cleaning polish etch process, however, adds equipment and handling costs. Nonetheless, without the cleaning polish etch process the surface of the glass substrate can be damaged by using only chemical etch due to the low resistance of the glass material to acid etching or overly aggressive caustic etch solutions.